



Embedded Systems Week

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October 7-14, 2022

Hybrid-Shanghai

CASES 2022

CASES

Call for Papers

International Conference on Compilers, Architectures, and Synthesis for Embedded Systems (CASES)
October 10 – October 12, 2022, Hybrid-Shanghai | Theme: AI at the Edge

CASES is a premier forum, where researchers, developers, and practitioners exchange information on the latest advances in design, optimization, validation, and applications of embedded systems, Internet of Things (IoT), and the emergent trend of integrating Artificial Intelligence into IoT (AIoT). The conference has a long tradition of showcasing leading edge research in these broad areas, covering topics including, but not limited to, hardware-software co-design and co-validation, edge intelligence, embedded architecture, memory/storage technology, security/reliability/predictability, energy-efficiency of embedded systems, and domain-specific hardware accelerators. We solicit submission of original research articles on these topics divided into five technical tracks. Each submission needs to specify one primary and one secondary track based on the relevance of the paper's technical content to the tracks.

TRACK 1: AI Systems and Applications of AI at Edge

Artificial Intelligence of Things (IoT), Edge intelligence, Architectures, accelerators, and compilers for artificial intelligence hardware; Applications of machine learning algorithms and techniques to embedded systems, IoT, and Cyber-Physical Systems (CPS); Neuromorphic and cognitive computing, analytics for embedded applications; and validation techniques for AI components.

TRACK 2: Embedded Systems and IoT/CPS Security, Safety, Reliability, and Energy-Efficiency

Secure architectures, hardware security, software security for embedded systems, IoT, and CPS; Architecture, design, and compiler techniques for energy-efficiency, reliability, and aging; Modeling, analysis, and optimization for timing and predictability; Validation, verification, testing, and debugging of embedded software.

TRACK 3: Memory and Storage

Memory system architecture; Persistent memory, Emerging memory technologies (e.g., ReRAM, MRAM, FeRAM, DNA); Caches, scratchpad memory, and compiler-controlled memory; Reconfigurable memory; Processing-in-memory; and storage systems.

TRACK 4: Accelerators, Emerging Technologies, and Applications

Synthesis, optimization, and design-space exploration of high-performance, low-power accelerators; Domain-specific accelerators; Compilers for accelerators; Biologically-inspired computing; Heterogeneous and domain-specific multi-core SoC; Approximate computing; Flexible, stretchable, and flexible hybrid electronics (FHE); Augmented/virtual reality.

TRACK 5: Architectures, Compilers, System-level Design

Embedded and mobile processor micro-architecture, Multi- and many-core processors, GPU architectures, Reconfigurable computing including FPGAs and CGRAs for embedded systems and IoT/CPS, Application-Specific processor design, 3D-stacked architectures; Networks-on-Chip (NoC) architectures; on-chip communication; I/O management in embedded systems; and compiler support for CPU, GPU, reconfigurable computing, compilation for memory, storage, and on-chip communications.

Regular Research Paper Submissions

Abstracts: March 31, 2022

Full Papers: April 7, 2022 (firm)

Work-in-Progress (WIP) Submissions

June 11, 2022 (firm)

Notification of Acceptance

July 5, 2022 (both types)

**All submissions are due by AOE time.*

Journal-integrated Publication Model: CASES 2022 has a dual publication model with five technical tracks. Regular research papers will be published in the IEEE Transactions on CAD and Work-in-Progress papers will be published in the ESWeek Proceedings. See details at <http://www.esweek.org/author-information>

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